



I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as First Class Mail, in an envelope addressed to: Box AF, Commissioner for Patents, Washington, DC 20231, on the date shown below.

Dated: December 3, 2002

Signature: MJDoherty

(Michael J. Doherty)

EXPEDITED PROCEDURE

Group Art Unit: 2827

Docket No.: TESSERA 3.0-078 DIV

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Fjelstad et al.

Application No.: 09/020,647

Filed: February 9, 1998

For: METHODS OF MAKING COMPLIANT
SEMICONDUCTOR CHIP PACKAGES

Group Art Unit: 2827

Examiner: D. Graybill

RECEIVED
DEC 12 2002
TC-2600 MAIL ROOM

AMENDMENT UNDER 37 CFR 1.116

Box AF

Commissioner for Patents
Washington, DC 20231

Dear Sir:

The present Amendment After Final is in response to the Final Office Action mailed July 25, 2002, in the above-identified U.S. patent application.

IN THE CLAIMS

42. (Twice Amended) The method according to Claim 35, further including plating a barrier metal atop the contacts of said semiconductor chip, wherein said barrier metal reduces voiding at an interface between the contacts and said bond ribbons.